

FEATURES:

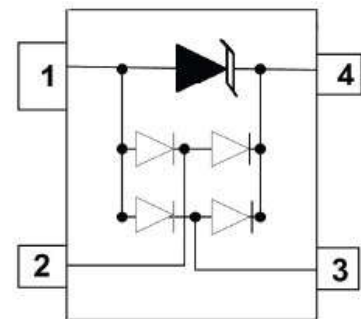
- ✧ Protects one bi-directional I/O line
- ✧ Low clamping voltage
- ✧ Low operating voltage: 5.0V
- ✧ ROHS compliant



SOT-143

MAIN APPLICATIONS

- ✧ Fire wire & USB
- ✧ Sensitive analog inputs
- ✧ Notebook computers
- ✧ Portable electronics
- ✧ LAN/WAN equipment
- ✧ Video line protection
- ✧ Microcontroller input protection



PIN Configuration

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)

MECHANICAL CHARACTERISTICS

- ✧ Package SOT-143
- ✧ Molding Compound Flammability Rating : UL 94V-O
- ✧ Quantity Per Reel : 3,000pcs
- ✧ Lead Finish : Lead Free
- ✧ Marking : E5R

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Storage temperature range	T _{stg}	-55 to +150	°C
Operating junction temperature range	T _j	-55 to +125	°C
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Peak pulse power dissipation on 8/20 μs waveform	P _{PP}	60	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	+/- 15	kV
ESD per IEC 61000-4-2 (Contact)		+/- 8	

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V _{RWM}				5.0	V
Reverse breakdown voltage	V _{BR}	I _T = 1mA	6.0			V
Reverse leakage current	I _R	V _{RWM} = 5V pin4 to pin1			1	μA
Clamping voltage (I/O pin to Ground)	V _C	I _{PP} = 1A, t _p = 8/20μs		9	10	V
		I _{PP} = 5A, t _p = 8/20μs		12	13	V
Junction capacitance	C _J	V _{RWM} = 0V, f = 1MHz Any I/O pin to Ground		0.8	1.0	pF
		V _{RWM} = 0V, f = 1MHz Between I/O pins		0.4	0.6	

RATINGS AND V-I CHARACTERISTICS CURVES (T_A=25°C, unless otherwise noted)

FIG.1: V- I curve characteristics (Uni-directional)

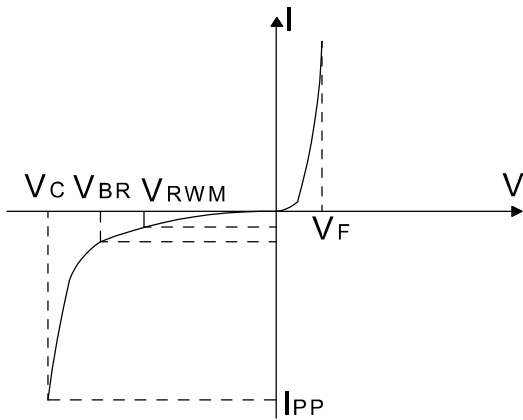


FIG.2: Pulse waveform (8/20μs)

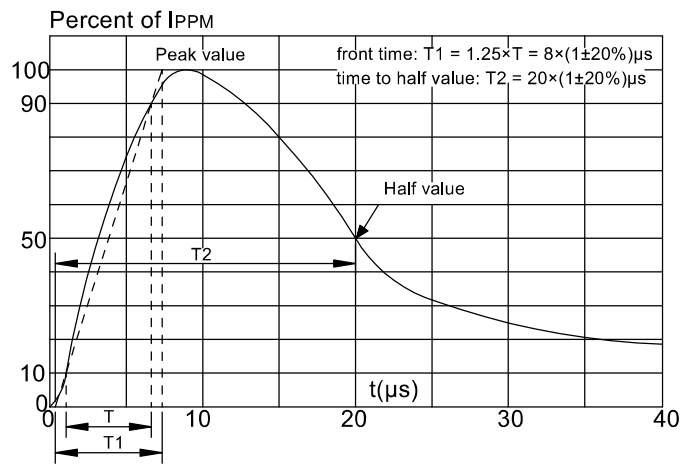


FIG.3: Pulse derating curve

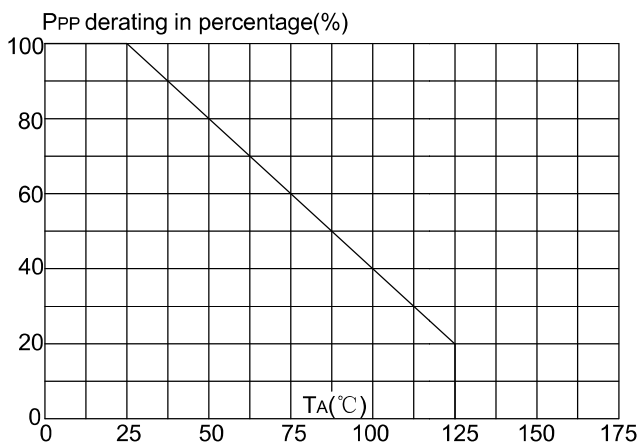
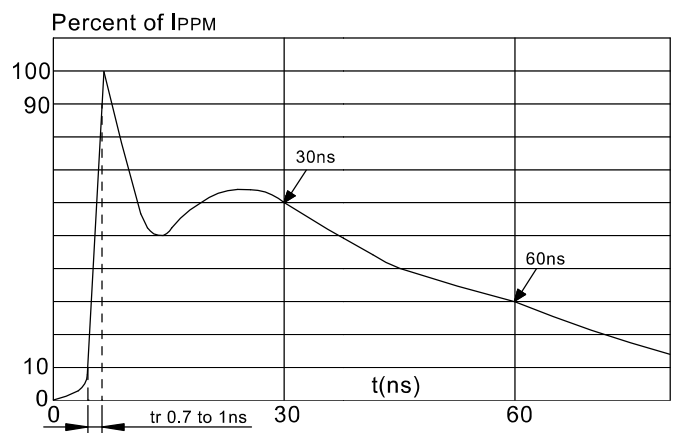
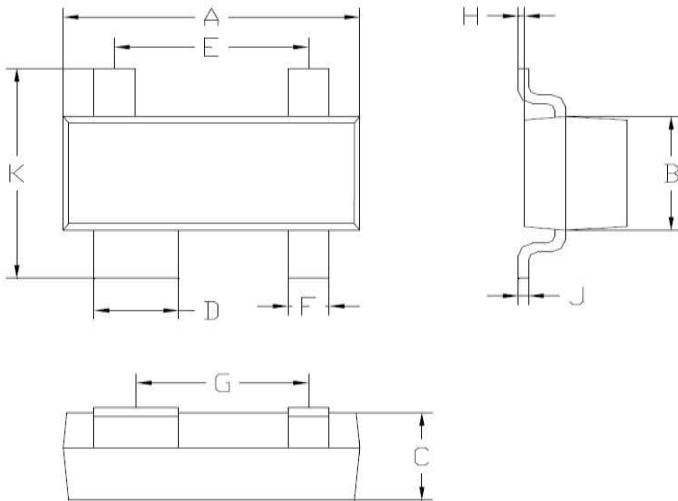


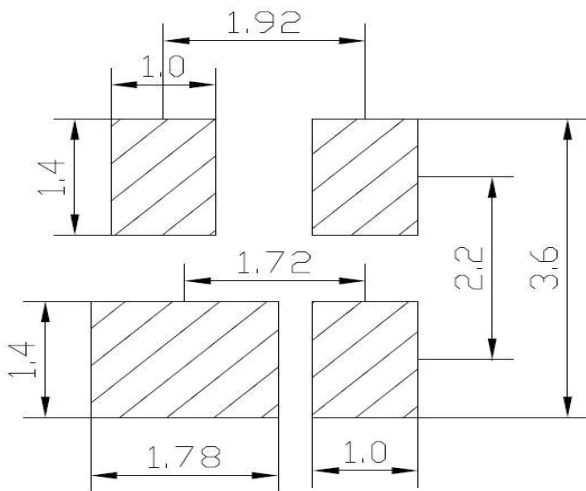
FIG.4: ESD clamping (8KV contact)



PACKAGE MECHANICAL DATA



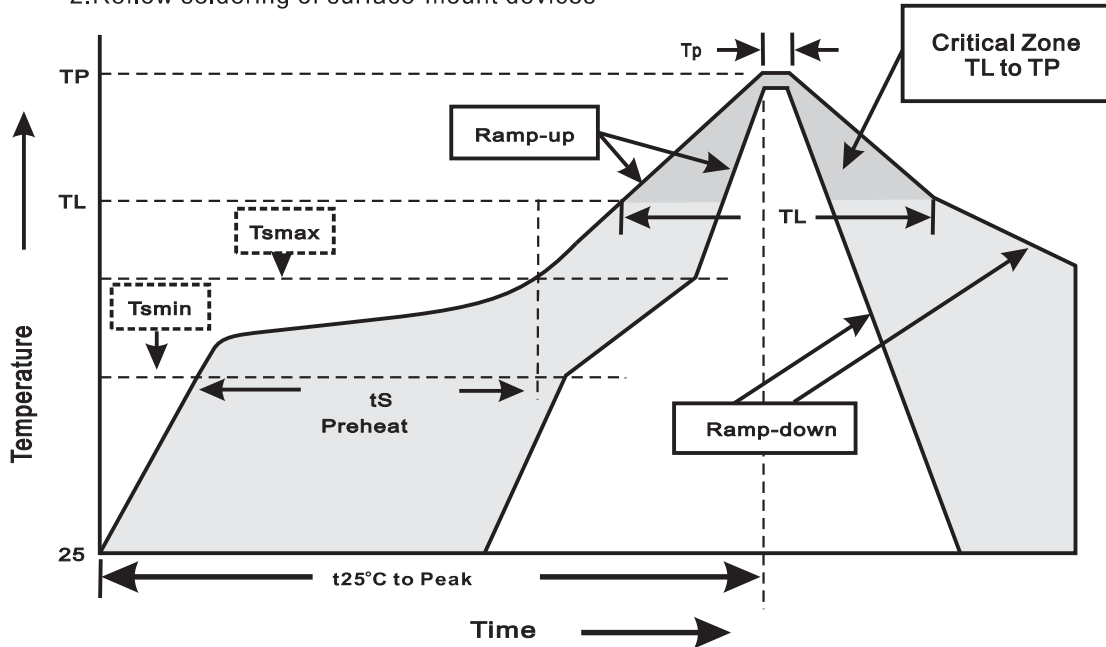
SOT-143		
Dim	Min	Max
A	2.70	3.10
B	1.10	1.50
C	0.9	1.1
D	0.78	0.88
E	1.80	2.00
F	0.37	0.43
G	1.59	1.79
H	0.02	0.1
J	0.05	0.15
K	2.20	2.60
ALL Dimensions in mm		



Unit : mm

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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